Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A protective film of a plasma display panel, comprising:

~~a main component of~~ magnesium oxide (MgO); and

~~an addition of~~ silicon (Si), wherein said protective film has less than 500ppm of silicon.

2. (Currently Amended) The protective film as claimed in claim 1, wherein ~~a content of the added silicon is preferably~~ said protective film comprises about 20ppm to 300ppm of silicon.

3. (Currently Amended) The protective film as claimed in claim 1, wherein the protective film further ~~includes~~ comprises: ~~an addition of~~

calcium (Ca) less than 50ppm[[,]];

iron (Fe) less than 50ppm[[,]]; and

aluminum (Al) less than 250ppm[[,]]

~~nickel (Ni) less than 5ppm;~~

~~natrium (Na) less than 5ppm; and~~

~~potassium (K) less than 5ppm~~.

4. (Currently Amended) The protective film as claimed in claim 1, wherein ~~a discharge gas containing xenon (Xe) more than 5% is sealed within the plasma display panel~~ said protective film has about 300ppm of silicon.

5. (Currently Amended) A method of fabricating a protective film of a plasma display panel, comprising ~~the step of~~:

forming the protective film having ~~a main component of~~ magnesium oxide (MgO) and ~~an addition of~~ silicon (Si), wherein said protective film has less than 500ppm of silicon.

6. (Currently Amended) The method as claimed in claim 5, wherein the protective film is formed ~~on the plasma display panel~~ by [[a]] vacuum deposition ~~process~~.

7. (Currently Amended) The method as claimed in claim 5, wherein the protective film is formed ~~on the plasma display panel~~ by one or more of the following processes: ~~any one process of a~~ chemical vapor deposition (CVD), [[a]] E-beam ~~process~~ processing, [[an]] ion-plating [[and]] or [[a]] sputtering.

8. (Currently Amended) The method as claimed in claim 5, wherein ~~a content of the added~~ said protective film has ~~silicon is preferably~~ about 20ppm to 300ppm of silicon.

9. (Currently Amended) The method as claimed in claim 5, wherein the protective film further comprises: ~~includes an addition of~~

calcium (Ca) less than 50ppm[[,]];

iron (Fe) less than 50ppm[[,]]; and

aluminum (Al) less than 250ppm.

10. (Currently Amended) The method as claimed in claim 5, ~~further comprising~~ wherein said protective film has about 300ppm of silicon ~~the step of:~~

~~sealing a discharge gas containing xenon (Xe) more than 5% within the plasma display panel~~.

11. (New) The protective film as claimed in claim 1, wherein the silicon compensates for secondary electron emission characteristics deteriorated by crystalline defects and impurities.

12. (New) The protective film as claimed in claim 1, wherein the silicon reduces a jitter value within the plasma display panel during address.

13. (New) The method as claimed in claim 5, wherein forming the protective film comprises adding silicon to a source material which comprises magnesium oxide by vacuum deposition.

14. (New) The method as claimed in claim 5, wherein forming the protective film comprises using both magnesium oxide and silicon as a source, wherein the silicon content is controlled by adjusting power applied to the silicon source.

15. (New) A plasma display panel, comprising:

an upper substrate;

a lower substrate across from the upper substrate;

a plurality of electrodes on the upper substrate;

a protective film on the upper substrate layer; and

a plurality of electrodes on the lower substrate, wherein said protective film comprises magnesium oxide and silicon.

16. (New) The plasma display panel as claimed in claim 15, wherein said protective film comprises at most 5000ppm silicon.

17. (New) The plasma display panel as claimed in claim 15, wherein said protective film comprises at most 500ppm silicon.

18. (New) The plasma display panel as claimed in claim 15, wherein said protective film comprises about 20 to 300ppm of silicon.

19. (New) The plasma display panel as claimed in claim 15, wherein the protective film further comprises:

calcium (Ca) less than 50ppm;

iron (Fe) less than 50ppm; and

aluminum (Al) less than 250ppm.

20. (New) The plasma display panel as claimed in claim 15, further comprising a discharge gas between the upper and lower substrates, wherein said discharge gas contains 5% Xenon or more.

21. (New) The protective film as claimed in claim 1, wherein the protective film further comprises:

nickel (Ni) less than 5ppm;

sodium (Na) less than 5ppm; and

potassium (K) less than 5ppm.

22. (New) The protective film as claimed in claim 3, wherein the protective film further comprises:

nickel (Ni) less than 5ppm;

sodium (Na) less than 5ppm; and

potassium (K) less than 5ppm.

23. (New) The method as claimed in claim 5, wherein the protective film further comprises:

nickel (Ni) less than 5ppm;

sodium (Na) less than 5ppm; and

potassium (K) less than 5ppm.

24. (New) The method as claimed in claim 9, wherein the protective film further comprises:

nickel (Ni) less than 5ppm;

sodium (Na) less than 5ppm; and

potassium (K) less than 5ppm.

25. (New) The plasma display panel as claimed in claim 15, wherein the protective film further comprises:

nickel (Ni) less than 5ppm;

sodium (Na) less than 5ppm; and

potassium (K) less than 5ppm.

26. (New) The plasma display panel as claimed in claim 19, wherein the protective film further comprises:

an upper dielectric layer on the upper substrate.